

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Wen-Kun Yang	11/23/2006
Jui-Hsien Chang	11/23/2006
RECEIVING PARTY DATA	
Name:	Advanced Chip Engineering Technology Inc.
Street Address:	No. 65, Guangfu N. Rd.
Internal Address:	Hukou Township
City:	Hsinchu County
State/Country:	TAIWAN
Postal Code:	303
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11608254
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	HK9390US
NAME OF SUBMITTER:	Michael A. Jaffe
Total Attachments: 2	
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OP \$40.00 11608254

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PATENT
REEL: 018600 FRAME: 0354

Practitioner's Docket No. HK9390US

PATENT

For: U.S. Rights
For: U.S. Application
By: Inventor

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration,

ASSIGNOR(S):

Wen-Kun YANG
(Given Name) (Middle Initial or Name) (Family or Last Name)
Address No. 47, Lane 6, An-Kang St., Hsin-Chu City, Taiwan, R.O.C.
Citizenship Taiwan, R.O.C.

Jui-Hsien CHANG
(Given Name) (Middle Initial or Name) (Family or Last Name)
Address No. 22, Alley 39, Lane 23, Wufong St., Jhndong Township, Hsinchu County 310, Taiwan, R.O.C.
Citizenship Taiwan, R.O.C.

hereby sells, assigns and transfers to:

ASSIGNEE: Name Advanced Chip Engineering Technology Inc.
Address No. 65, Guangfu N. Rd., Hukou Township, Hsinchu County 303,
Taiwan, R.O.C.
Corporation of Taiwan, R.O.C.

and the successors, assigns and legal representatives of the ASSIGNEE the entire right, title and interest for the United States and its territorial possessions in and to any and all improvements which are disclosed in the invention entitled:

Image Sensor Module

and which is found in (37 C.F.R. § 3.21) U.S. patent application executed on even date herewith or [X] in Application No. _____, filed on _____ and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, or substitute thereof, and as to letters patent any reissue or re-examination thereof.

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

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ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I have hereunto set hand and seal.

Date: NOV. 23, 2006

Wen-Kun Yang
Signature of: Wen-Kun YANG
(Given Name, Middle Initial or Name, Family or Last Name)

Date: Nov. 23, 2006

Jui-Hsien Chang
Signature of: Jui-Hsien CHANG
(Given Name, Middle Initial or Name, Family or Last Name)

(Assignment of Invention—page 2 of 2)